



TARGET THICKNESS: 0.125"
NUMBER OF LAYERS: 12

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

12 Layer StackUp (0.125") L12-125-1oz1oz		Thickness (inches)
Layer 1	1 oz foil plated to approximate* thickness 0.0024"	0.0024
Prepreg	Bonding ply (3x2116) Average Dielectric Constant 4.5	0.0126
Layer 2	1 oz foil thickness	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.01
Layer 3	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 4	1 oz foil thickness	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.01
Layer 5	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 6	1 oz foil thickness	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.01
Layer 7	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 8	1 oz foil thickness	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.01
Layer 9	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 10	1 oz foil thickness	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.01
Layer 11	1 oz foil thickness	0.0014
Prepreg	Bonding ply (3x2116) Average Dielectric Constant 4.5	0.0126
Layer 12	1 oz foil plated to approximate* thickness 0.0024"	0.0024
"Thickness does not include soldermask or surface finish"		0.1252

NOTES: